

ITW

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

GERD MARXSEN AXEL PREUSSE MARKUS NOPPER FRANK MAUERSBERGER

Serial No.: 10/666,195

Filed: September 19, 2003

For: METHOD OF ELECTROPLATING
COPPER OVER A PATTERNED
DIELECTRIC LAYER TO ENHANCE
PROCESS UNIFORMITY OF A
SUBSEQUENT CMP PROCESS

Examiner: Jennifer M. Dolan

Group Art Unit: 2813

Att'y Docket: 2000.109000/DE0133

Customer No.: 23720

RESPONSE TO OFFICE ACTION DATED FEBRUARY 17, 2005

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

CERTIFICATE OF MAILING 37 C.F.R 1.8

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below:

April 12, 2005

Date

//aux faul Signature

This paper is submitted in response to the Office Action dated February 17, 2005, for which the three-month date for response is May 17, 2005.

No fees are believed to be due in connection with the present paper. However, should any fees be required under 37 C.F.R. §§ 1.16 to 1.21, the Director is authorized to deduct such fees from the Advanced Micro Devices, Inc. Deposit Account No. 01-0365/DE0133. In the event the monies in that account are insufficient, the Director is authorized to withdraw funds from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/2000.109000.

Reconsideration of the application in view of the following amendments and remarks is respectfully requested.